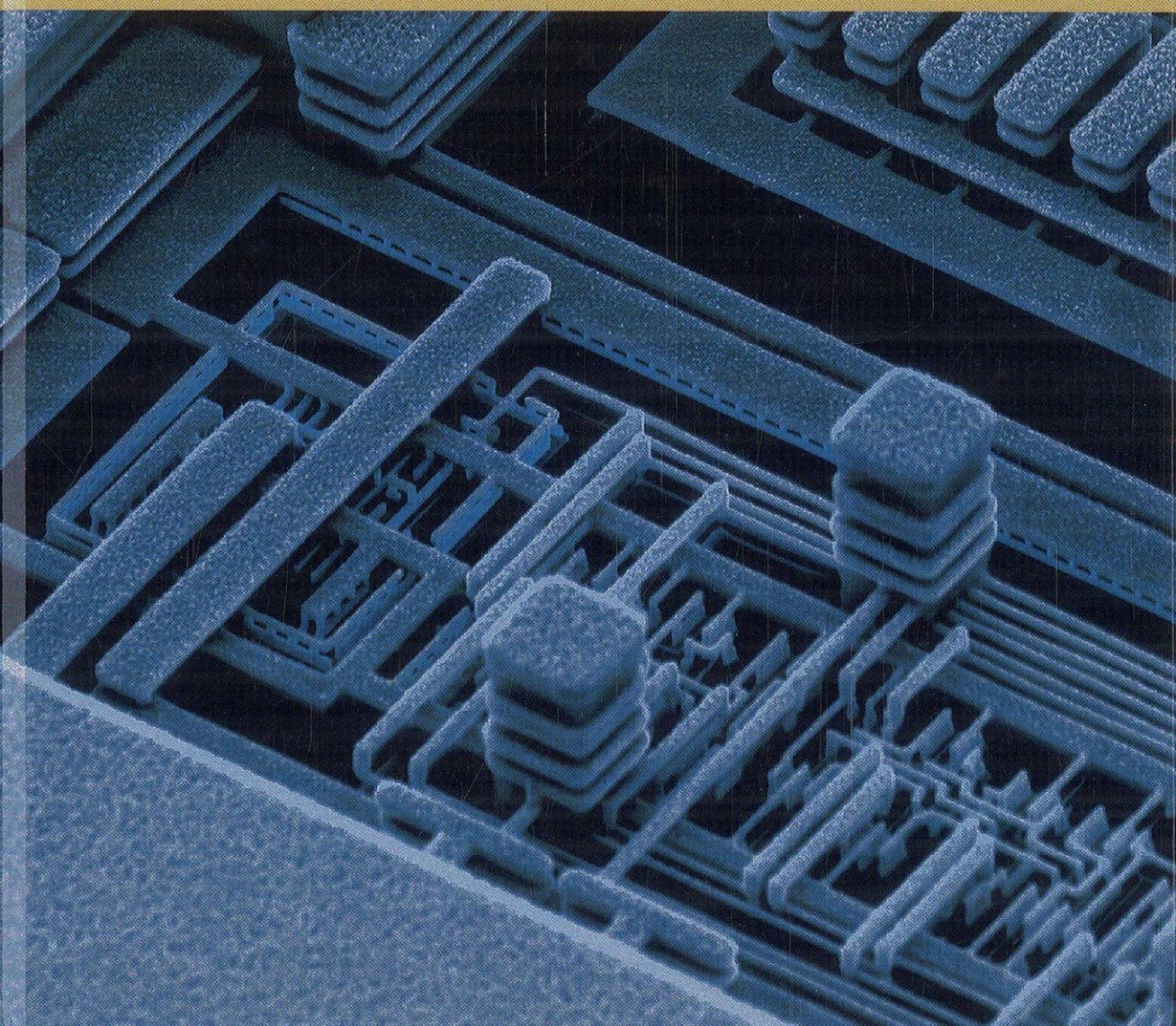


Second Edition

Fundamentals of

Modern VLSI Devices

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